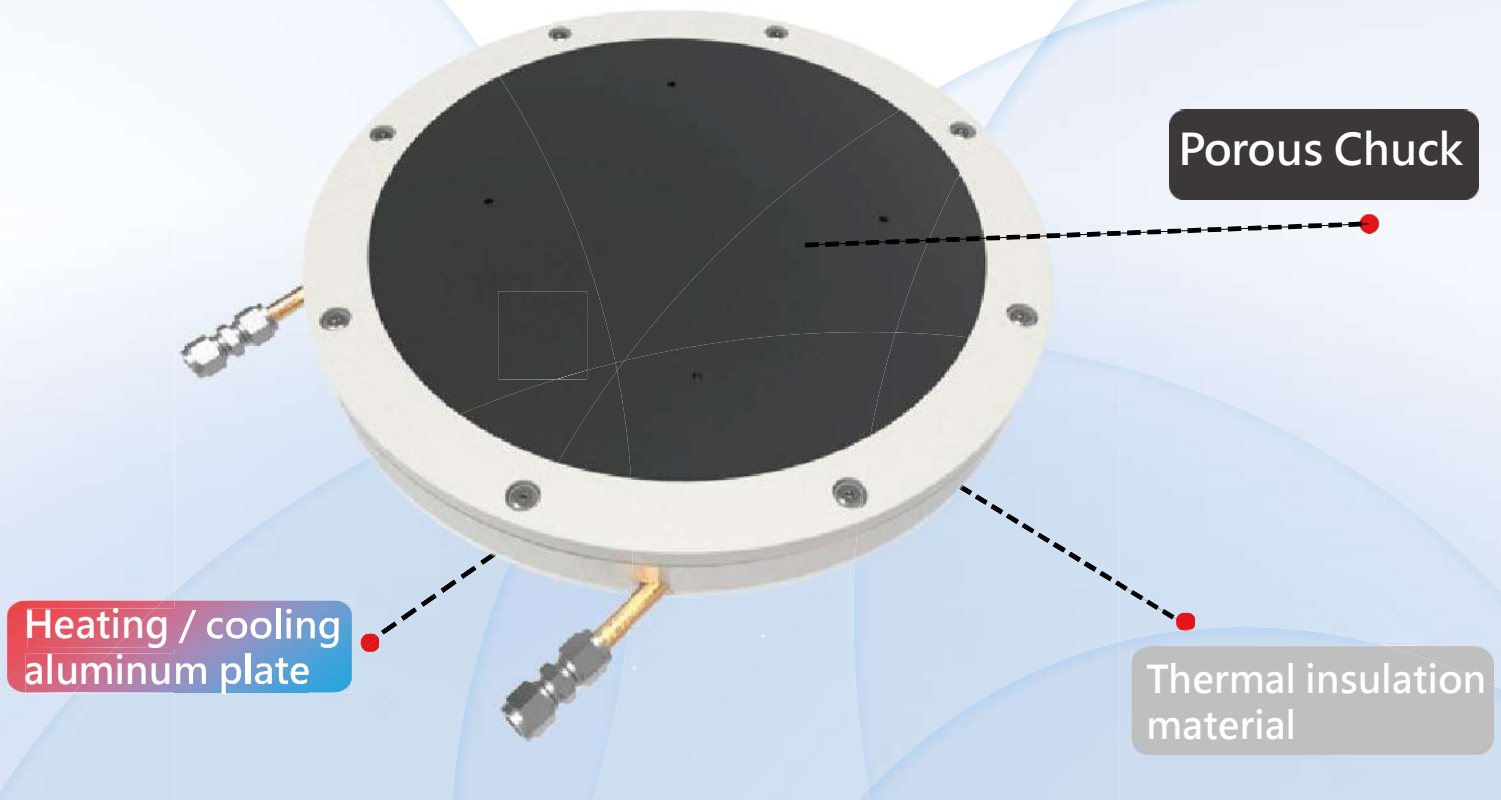


# Porous Ceramic Thermal Chuck



## Applications

1. Wafer-level thermo bonding
2. Electrical conductivity endurance test of wafers while being heated

## Features

1. Industry's first integrated heating / cooling porous ceramic chuck
2. Three-zone Temp. control design, uniformity UP
3. High throughput



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# Specifications

ITEM	SPECIFICATION
Pore diameter range	15 $\mu$ m - 40 $\mu$ m
Porous material	SiC
Size	$\phi$ 150 - $\phi$ 300 (6 " -12 ")
Insulation material	10 <sup>6</sup> ~10 <sup>9</sup> $\Omega$
Temp.distributions	$\pm 2$ °C (depends on the specification)
Temp. setting range	200 °C

